

ABSTRACT

In an electronic component in which a semiconductor device such as a light emitting diode is encapsulated by an encapsulation resin and a manufacturing method of the same, formation of flash on occasion of filling a resin is prevented. The semiconductor device 1 (SIC) is mounted in a reception concavity 3 of a base member 2, and the encapsulation resin is filled into the reception concavity 3. After mounting the semiconductor device 1 in the reception concavity 3 and before filling the encapsulation resin into the reception concavity 3, a stopper resin layer 6 is formed on a top face 2a of the base member 2 along a circumference of an aperture of the reception concavity 3 by applying a resin. Since the circumference of the aperture of the reception concavity 3 including electric conductive patterns 4 and the base member 2 is covered by the stopper resin layer 6, even when the encapsulation resin having low viscosity is filled into the reception concavity, leakage or proceeding due to capillarity of the encapsulation resin is prevented by the stopper resin layer 6. As a result, no flash of leaked encapsulation resin is formed.